## Claims

- 1. A transparent conductive multi-layer structure which comprises a smooth base material, a transparent conductive layer formed on the smooth base material by coating, an auxiliary electrode layer formed in a pattern on the transparent conductive layer, and a transparent substrate joined to the transparent conductive layer and auxiliary electrode layer through an adhesive layer; the smooth base material being peelable from the transparent conductive layer.
- 2. The transparent conductive multi-layer structure according to claim 1, wherein said auxiliary electrode layer has a pattern in the shape of a lattice, the shape of a mesh, the shape of a honeycomb, the shape of parallel lines or the shape of the teeth of a comb.
- 3. The transparent conductive multi-layer

  20 structure according to claim 1 or 2, wherein said

  auxiliary electrode layer comprises at least one

  selected from fine metal particles, fine carbon

  particles and fine ruthenium oxide particles, or at

  least one selected from fine metal particles, fine

  25 carbon particles and fine ruthenium oxide particles and

  a binder component.

- 4. The transparent conductive multi-layer structure according to any one of claims 1 to 3, wherein said auxiliary electrode layer comprises a first

  5 auxiliary electrode layer formed on the transparent conductive layer and a second auxiliary electrode layer formed on the first auxiliary electrode layer; said first auxiliary electrode layer comprising at least one selected from fine carbon particles, fine ruthenium

  10 particles and fine ruthenium oxide particles and a binder component, and said second auxiliary electrode layer comprising fine metal particles and a binder component.
- 5. The transparent conductive multi-layer structure according to any one of claims 1 to 4, which further comprises a transparent coat layer formed by coating between i) said auxiliary electrode layer and said transparent conductive layer at its areas standing not covered with said pattern-shaped auxiliary electrode layer and ii) said adhesive layer.
- 6. The transparent conductive multi-layer structure according to any one of claims 1 to 5, wherein said transparent conductive layer comprises conductive fine oxide particles of from 1 to 100 nm in average

particle diameter and a binder component.

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- 7. The transparent conductive multi-layer structure according to any one of claims 1 to 6, wherein said transparent conductive layer has been subjected to rolling to make the conductive fine oxide particles dense.
- 8. The transparent conductive multi-layer

  structure according to any one of claims 1 to 7, wherein said adhesive layer is mixed with at least one additive selected from an ultraviolet absorber, a dehydrating agent and a deoxidizer.
- 9. A process for manufacturing a transparent conductive multi-layer structure, which comprises:

coating a smooth base material thereon with a transparent conductive layer forming coating fluid prepared by dispersing conductive fine oxide particles in a solvent, followed by drying and optionally curing to form a transparent conductive layer; a base material peelable from the transparent conductive layer being used as the smooth base material;

forming an auxiliary electrode layer in a pattern 25 on the transparent conductive layer; and

joining with an adhesive a transparent substrate

to the auxiliary electrode layer formed and to the transparent conductive layer at its areas standing not covered with the auxiliary electrode layer.

- 5 10. The process for manufacturing a transparent conductive multi-layer structure according to claim 9, wherein, after the coating with said transparent conductive layer forming coating fluid, followed by drying, the transparent conductive layer is subjected to rolling.
- 11. The process for manufacturing a transparent conductive multi-layer structure according to claim 9 or 10, wherein said auxiliary electrode layer is formed by printing a auxiliary electrode layer forming paste prepared by dispersing in a solvent or a solvent containing a binder at least one selected from fine metal particles, fine carbon particles and fine ruthenium oxide particles, followed by curing.

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12. The process for manufacturing a transparent conductive multi-layer structure according to any one of claims 9 to 11, wherein said auxiliary electrode layer and said transparent conductive layer at its areas standing not covered with said pattern-shaped auxiliary electrode layer are coated thereon with a transparent

coat layer forming coating fluid containing a binder, followed by curing to form a transparent coat layer, and thereafter said transparent substrate is joined with an adhesive to the transparent coat layer.

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- 13. The process for manufacturing a transparent conductive multi-layer structure according to any one of claims 9 to 12, wherein said conductive fine oxide particles of said transparent conductive layer forming coating fluid has an average particle diameter of from 1 to 100 nm.
- 14. The process for manufacturing a transparent conductive multi-layer structure according to any one of claims 9 to 13, wherein said transparent conductive layer forming coating fluid contains a binder.
  - 15. The process for manufacturing a transparent conductive multi-layer structure according to any one of claims 9 to 14, wherein said adhesive is mixed with at least one additive selected from an ultraviolet absorber, a dehydrating agent and a deoxidizer.
- 16. A device which comprises the transparent
  25 conductive multi-layer structure according to any one of
  claims 1 to 8, from which the smooth base material has

been peeled off to have the transparent conductive layer and the auxiliary electrode layer which are joined to the transparent substrate through the adhesive layer.

5 17. The device according to claim 16, which is a dye-sensitized solar cell or an organic electroluminescent device.